

Advances in Thin Film Metrology for MRAM

by Mark Willingham ADE Corporation



Thin Film Metrology for Magnetic Measurements

What's Available – Limitations?

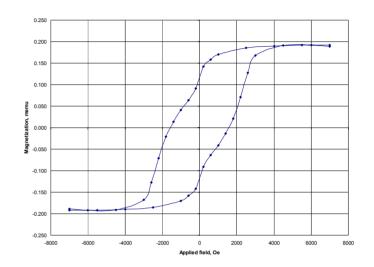
- Absolute Measurement
- Mapping
- Process Metrology used in GMR today
- Challenges of MRAM for Metrology
- Current MRAM Metrology

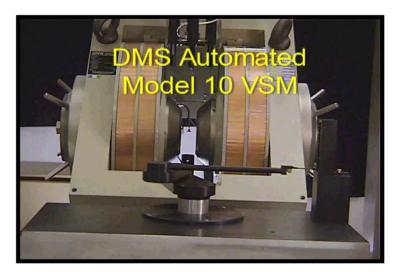


Magnetics to Absolute Ref

Vibrating Sample Magnetometer

- ◆ 1 x 10⁻⁷ emu Sensitivity
- High Precision Vector performance
- Direct field control Speed
- Versatile, Sophisticated software
- Temperature available
- Absolute Moment measurement
- Sample size limited to ~8mm







Magnetics to Absolute Ref

SQUID

- ◆ 1 x 10⁻⁹ emu Sensitivity
- High Stability
- Helium Temperature range
- Very Slow measurement
- Sample size limited

0.010 0.020 0.020 0.0000 0.0000 0.0000 0.0000 0.0000 0.0000 0.0000 0.00000 0.00000

AGFM

- ◆ 1 x 10⁻⁸ emu Sensitivity
- No Temperature capability
- ♦ Fragile in use
- Sample size limited



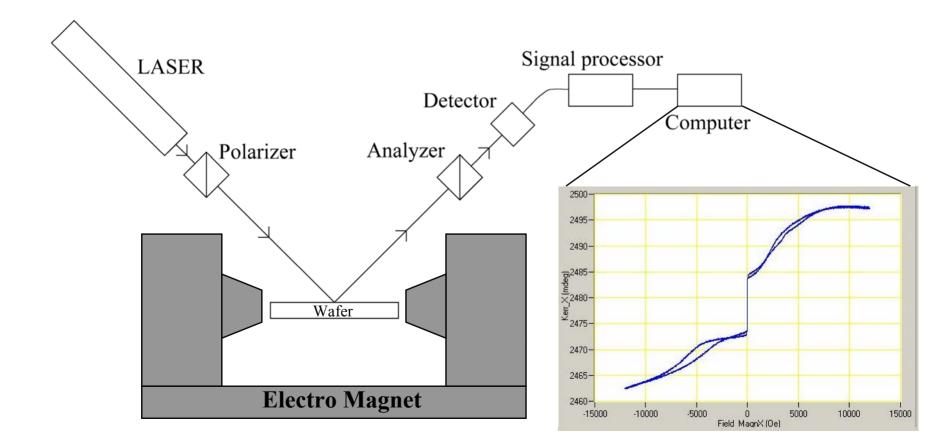
Not Enough, Need More!

Development and Production

- Wafer Level measurement
 - Need to Map
 - Eliminate Cutting
- Measure on Product
 - Non Contact
 - High Speed Keep up with production
- Combine Measurement Needs
- Ready for Fab Use in Clean room



Kerr Effect Measurement (Longitudinal)





Kerr Effect Measurement

- Magneto optic Non Contact
- No sample size limitation
- Spot measurement on wafer
- See multiple interacting layers
- Penetration depth limited
- No absolute layer thicknesses
- Small Signal available
- Environmental sensitivity



Kerr Effect Magnetometer

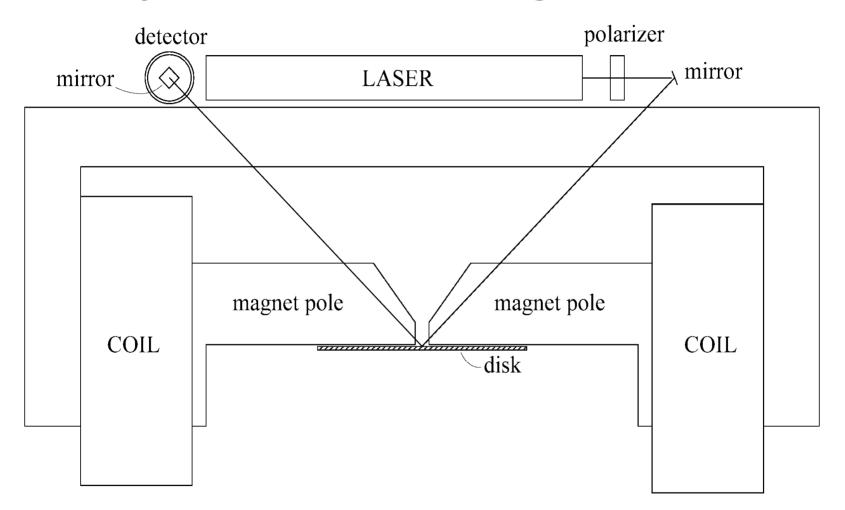


Used in GMR process

- Non-contact measurement of magnetic parameters
- Single point or multi-point
- High Field up to 12,000 Oe
- High Resolution 0.010e
- Fast 10 seconds per measurement

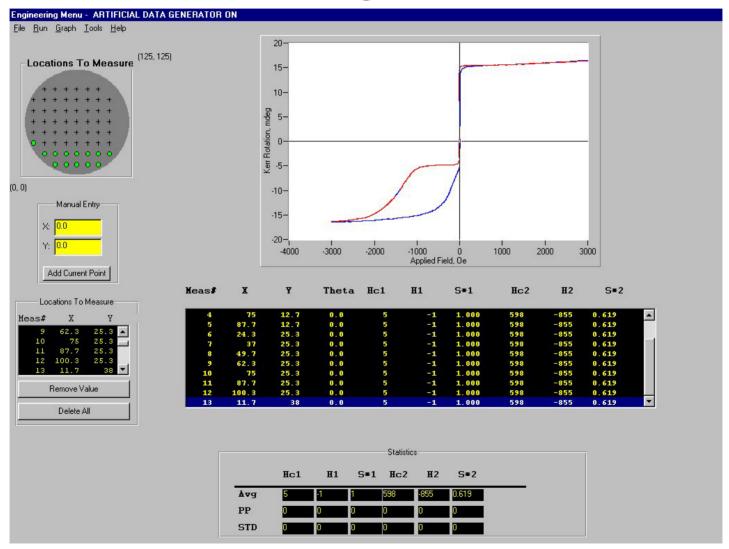


Layout of Kerr Effect Magnetometer





Need Strong Interface



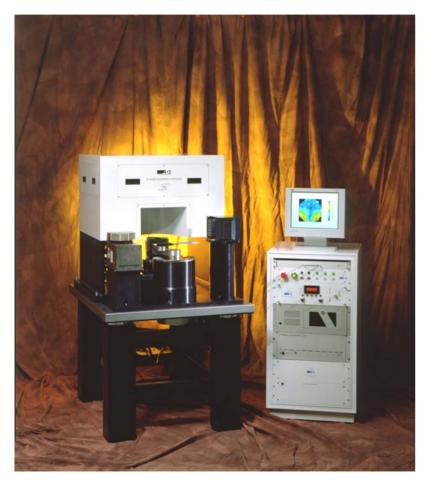


MRAM Metrology New Challenges for Kerr

- New Processes
- Active Field Control
 - High Field w/ Low Field Resolution
 - Free and Pinned layer
- Multi Axis Field
- Thinner Layers
- Small Packing Ratio
- Additional Top Layers
- Substrate Size Increasing?



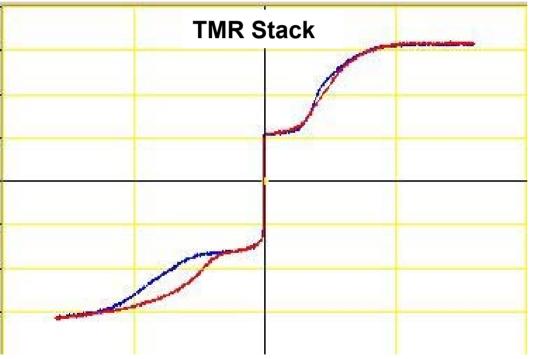
Kerr Effect Magnetometer for MRAM



- Full Wafer Access up to 300 mm
- Non Contact
- Active Field Control
- Proven Technology
- Vector Field Capable
- Vector Kerr



Kerr Effect Magnetometer for MRAM



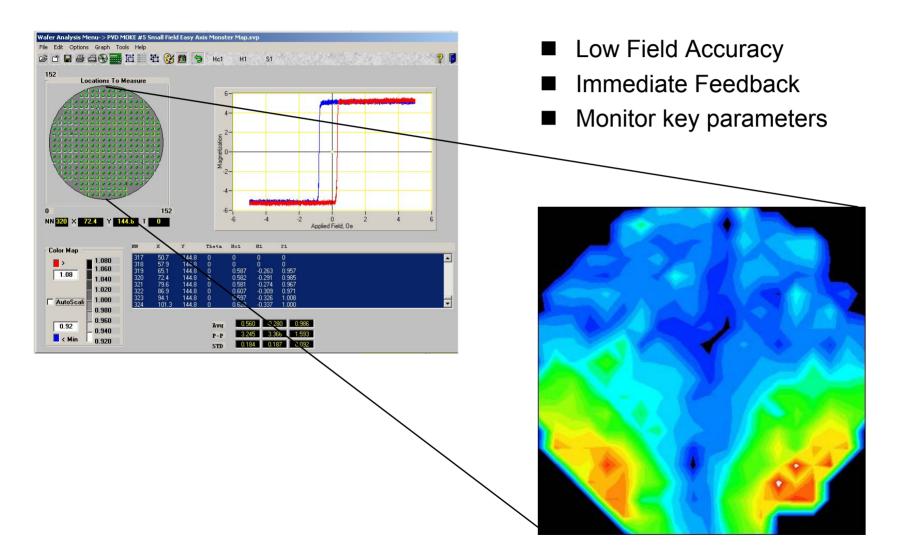
Set High Field

- Excite both Free and Pinned Layers to see Interaction
- Penetrate Multiple layers

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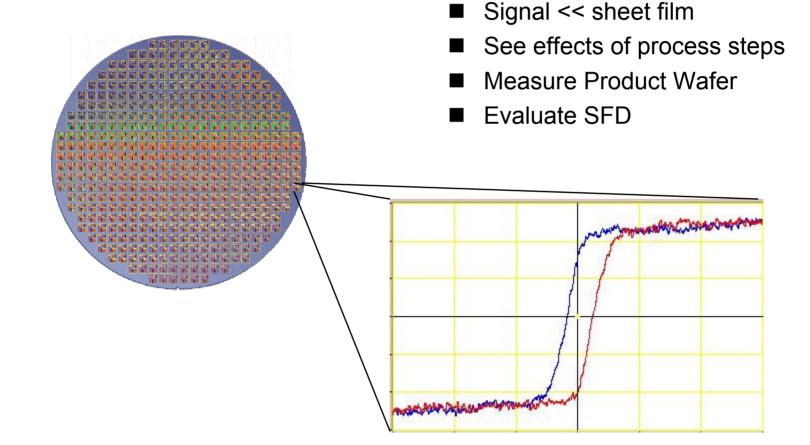


Uniformity of Sheet Film





Scan Patterned MRAM Array

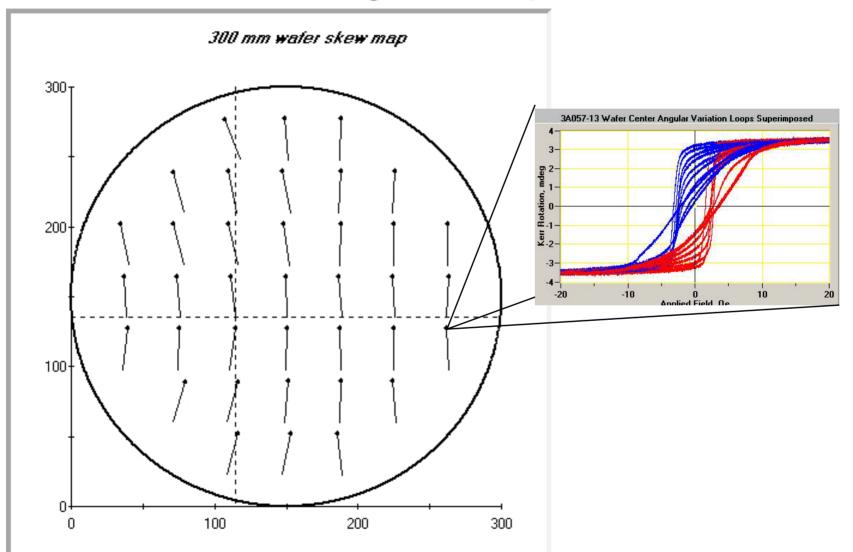


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Evaluate Angular Properties



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MRAM Kerr Effect Magnetometer



Operation

- Load wafer by hand or Robot
- Auto Z Position Cap gage Feedback
- Measure Selected Locations
- Extract Parameters
- Access whole wafer
- User Defined Mapping
- Modular Design



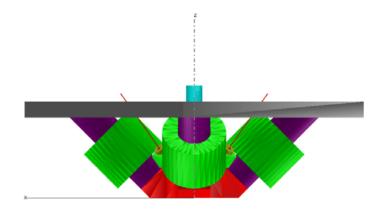
Active Field Control

Active Control = True Zero Field

- Hall Probe Feedback
- Pole Remanence
- Earth field
- Other stray fields
- Real Time Feedback
 - Static

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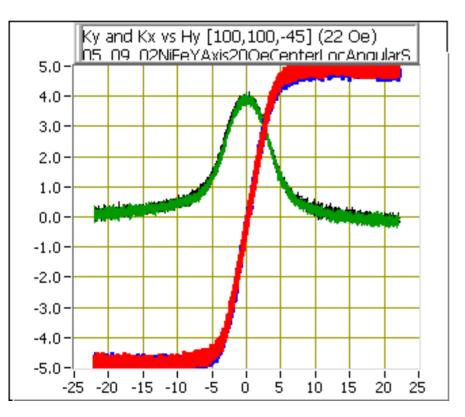
- Sweeping
- Programmable Sweep Rate



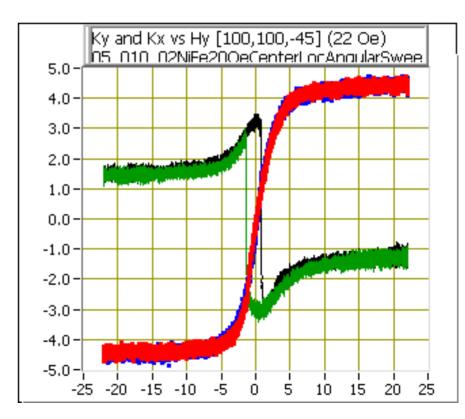


Vector Kerr

1 Oe Cross Field

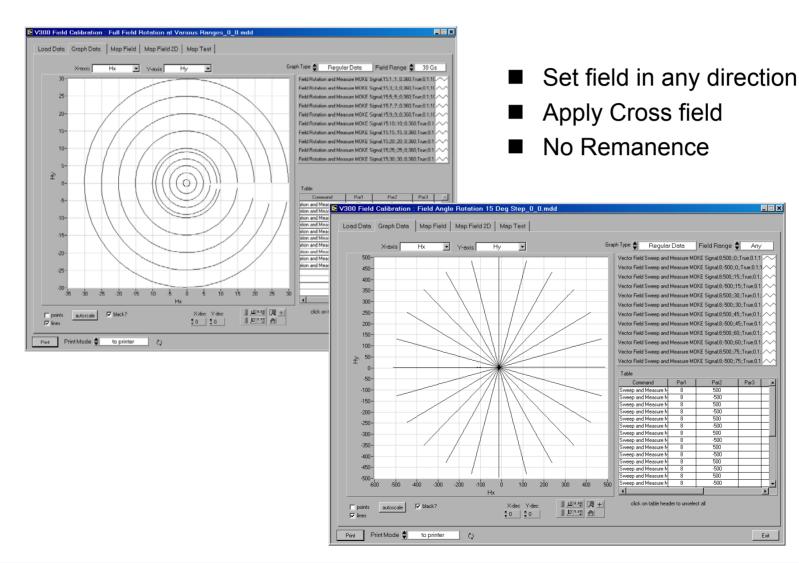


Active Field Control





Direct Vector Field Control

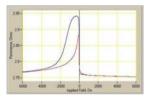




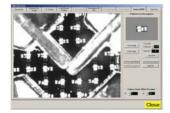
Supports multiple functions

Wafer Measurement Platform

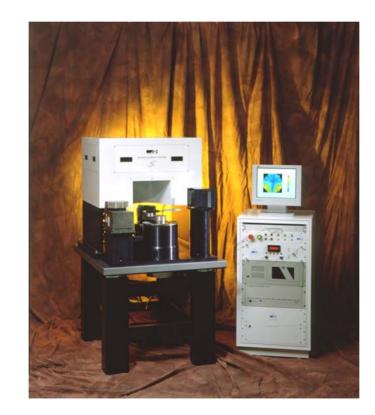
4 Point Probing Module



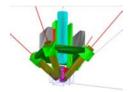
Test Pad Probing Module



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Kerr Effect Module





Wafer Automation





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